

Parallel Plate Electrostatic Actuation for High-Resolution Deformable Mirrors

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CfAO TMT MEMS DM WS

Outline

Electrostatic MEMS DM architectures

Electrostatics and mechanics of actuators

Scaling rules and real-world limits

Case study: Extending stroke

Electrostatic MEMS DM architectures



Edge-supported membranes



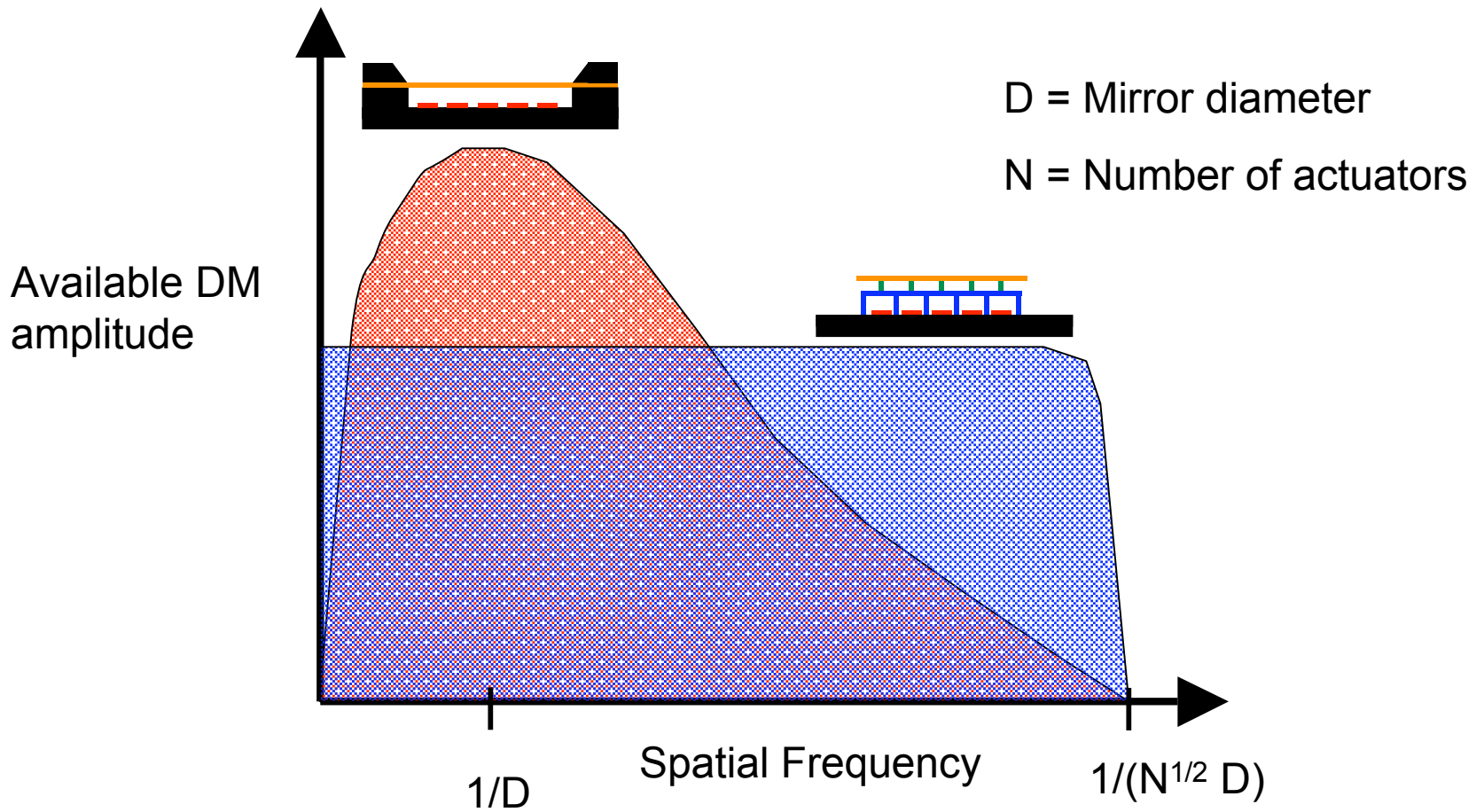
Post-supported membranes



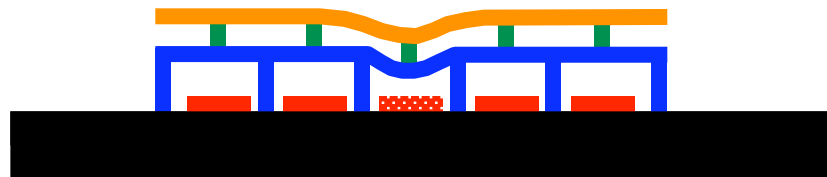
Advantages and disadvantages

	+	-
 A cross-sectional diagram of a piezoelectric actuator. It shows a black substrate with a central rectangular cavity. Inside the cavity, there is a thin orange layer on top and a red dashed line below it, representing a piezoelectric layer and a conductive layer respectively.	<p>Economical to develop Large stroke @ low order Customizable</p>	<p>Sensitive to sound Frame-induced warp Low stroke @ high order</p>
 A top-down diagram of a micro-actuator array. It shows a black substrate with a grid of small blue rectangular actuators. Each actuator has a red base and a blue top. A horizontal orange bar is positioned above the actuators, representing a common electrode or frame.	<p>Scalable to many actuators High natural frequency Batch producible</p>	<p>Expensive to develop Fabrication induced stress Limited coating options</p>

Controllable spatial frequency comparison

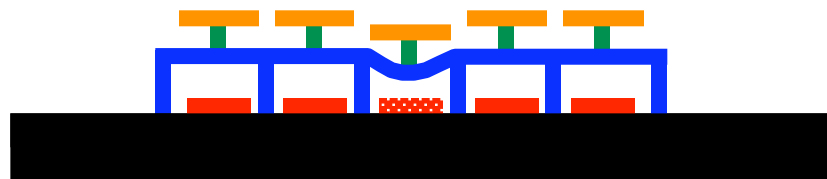


Boston University & Boston Micromachines Corporation Design



Continuous

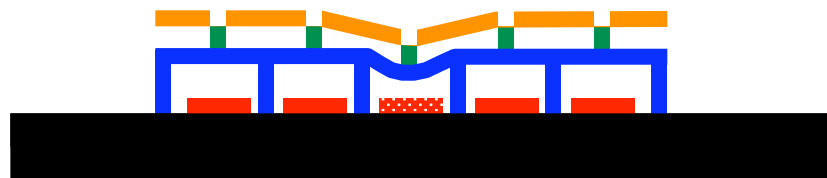
To get the same AO
fitting error
(Kolmogorov
turbulence)



Piston

$$N_{\text{piston}}/N_{\text{continuous}} = 6.2$$

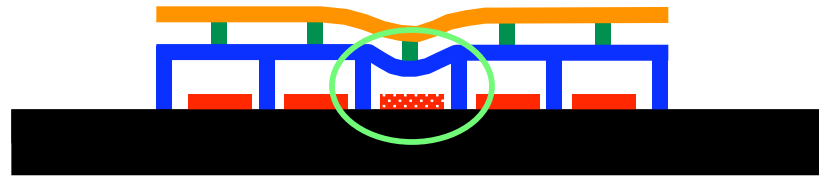
$$N_{\text{tip-tilt}}/N_{\text{continuous}} = 1.8$$



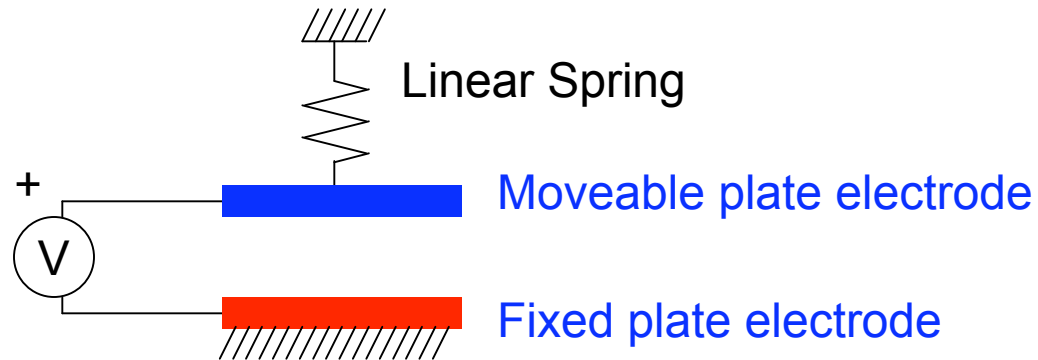
Tip-Tilt

(C. Max, CfAO website)

Electrostatic actuators

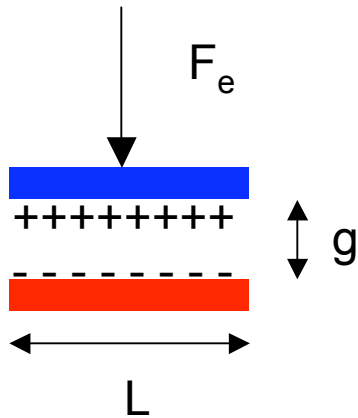


Simplified actuator model:



Electrostatic attraction force

Parallel plates form a capacitor



$$C = \frac{\epsilon_o \epsilon_r L w}{g}$$

ϵ_o = permittivity of free space ($8.8e^{-12}$ F/m)

ϵ_r = medium dielectric constant (1 for air)

L = plate length (m)

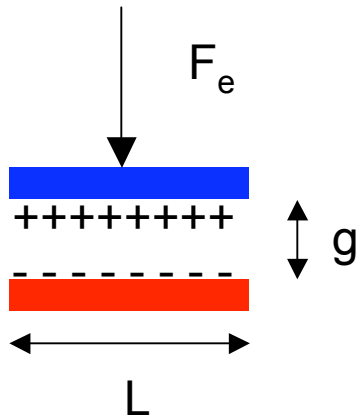
w = plate width (m)

g = gap (m)

Electrostatic attraction force

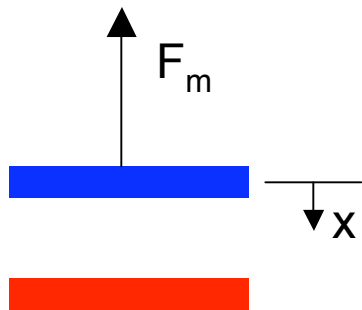
Potential energy: $U = \frac{1}{2} CV^2 = \frac{\epsilon_0 \epsilon_r LwV^2}{2g}$

V = applied voltage (V)



Electrostatic force: $F_e = \frac{dU}{dg} = \frac{\epsilon_0 \epsilon_r LwV^2}{2g^2}$

Mechanical restoring force



$$F_m = kx$$

$$x = g_o - g$$

x = displacement

g_o = initial gap

Static equilibrium: $\Sigma F=0$

$$F_e = F_m$$

$$\frac{\epsilon_o \epsilon_r L W V^2}{2(g_o - x)^2} = kx$$

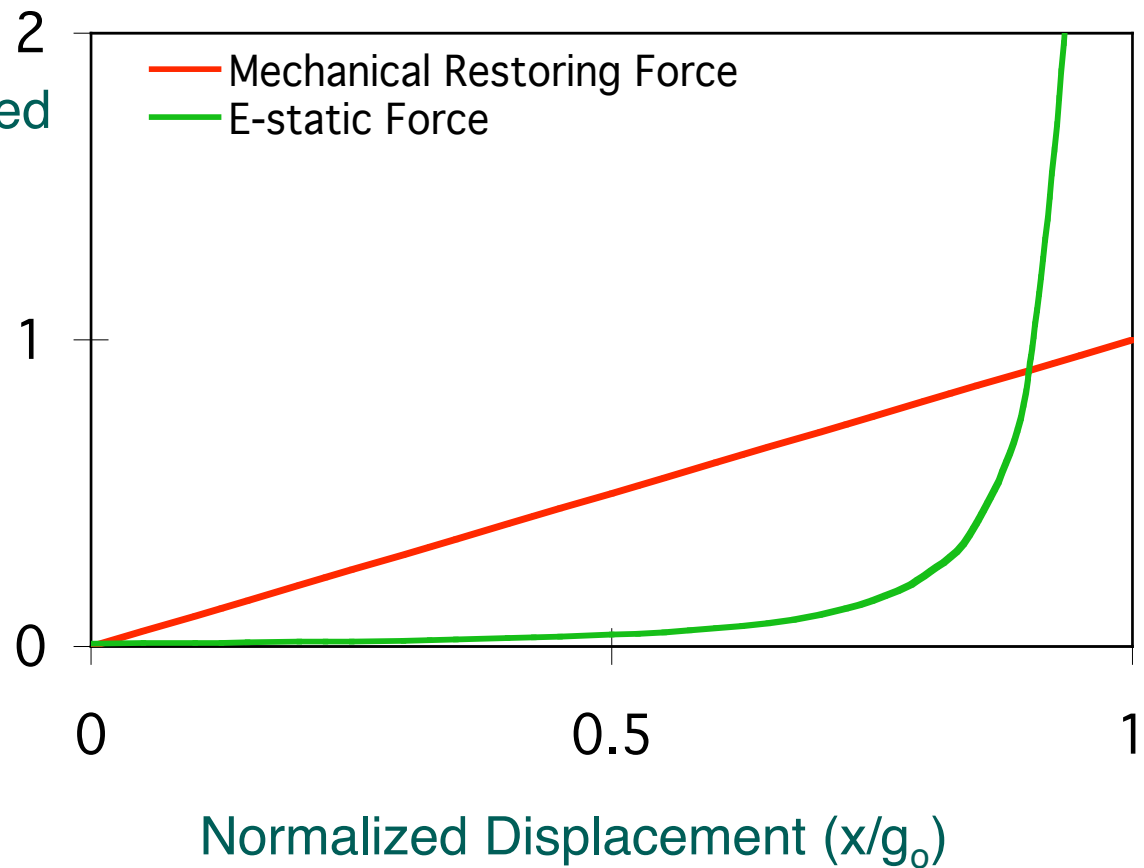
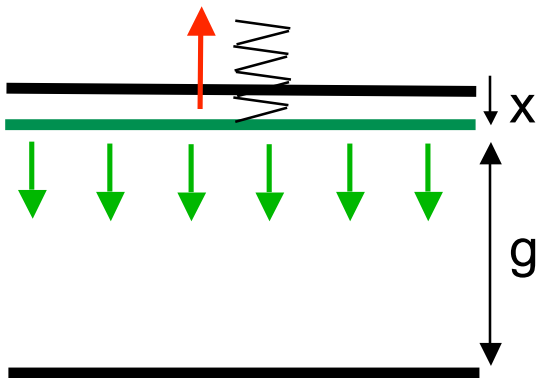
Cubic equation for x as a function of V^2

Graphical representation of equilibrium

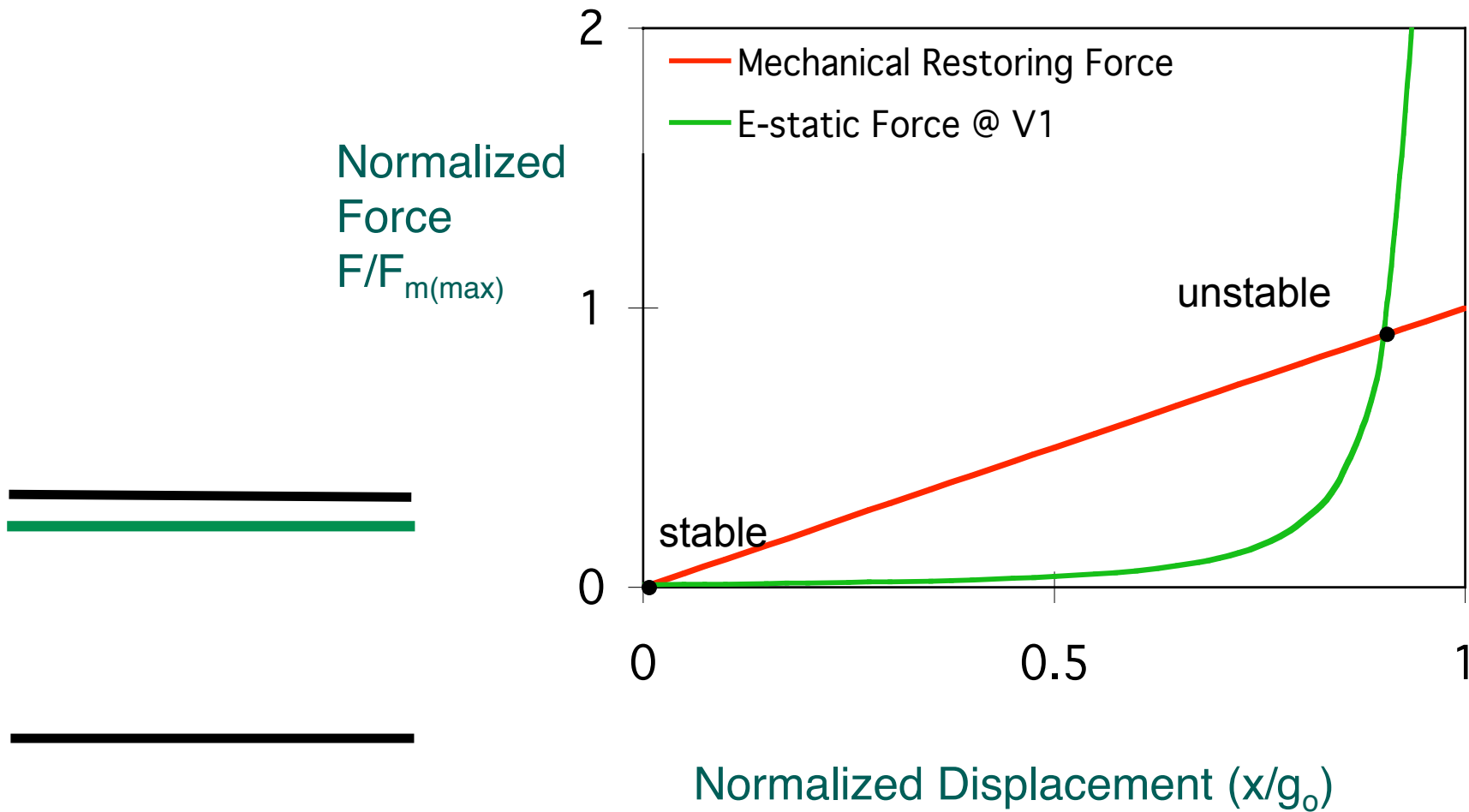
$$F_m = kx$$

$$F_E = \frac{\epsilon_o \epsilon_r L W V^2}{2(g_o - x)^2}$$

Normalized
Force
 $F/F_{m(\max)}$



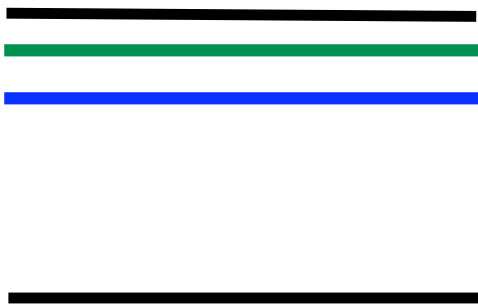
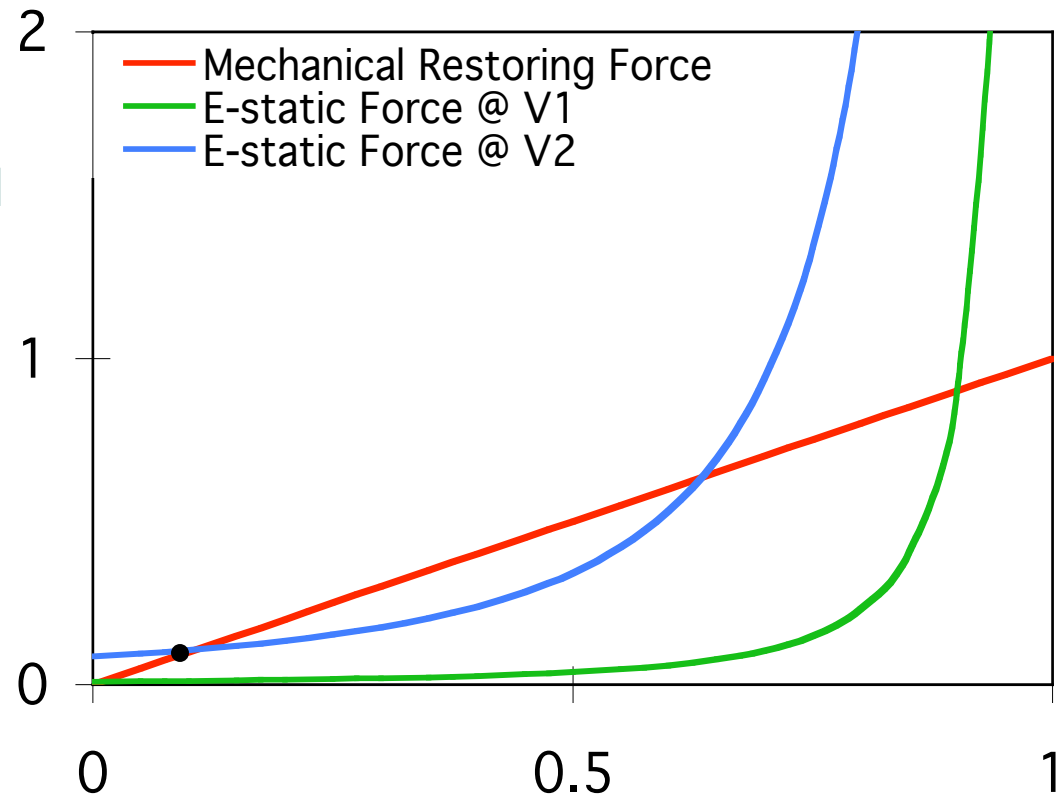
Graphical representation of equilibrium



Graphical representation of equilibrium

Increasing V

Normalized Force
 $F/F_{m(max)}$

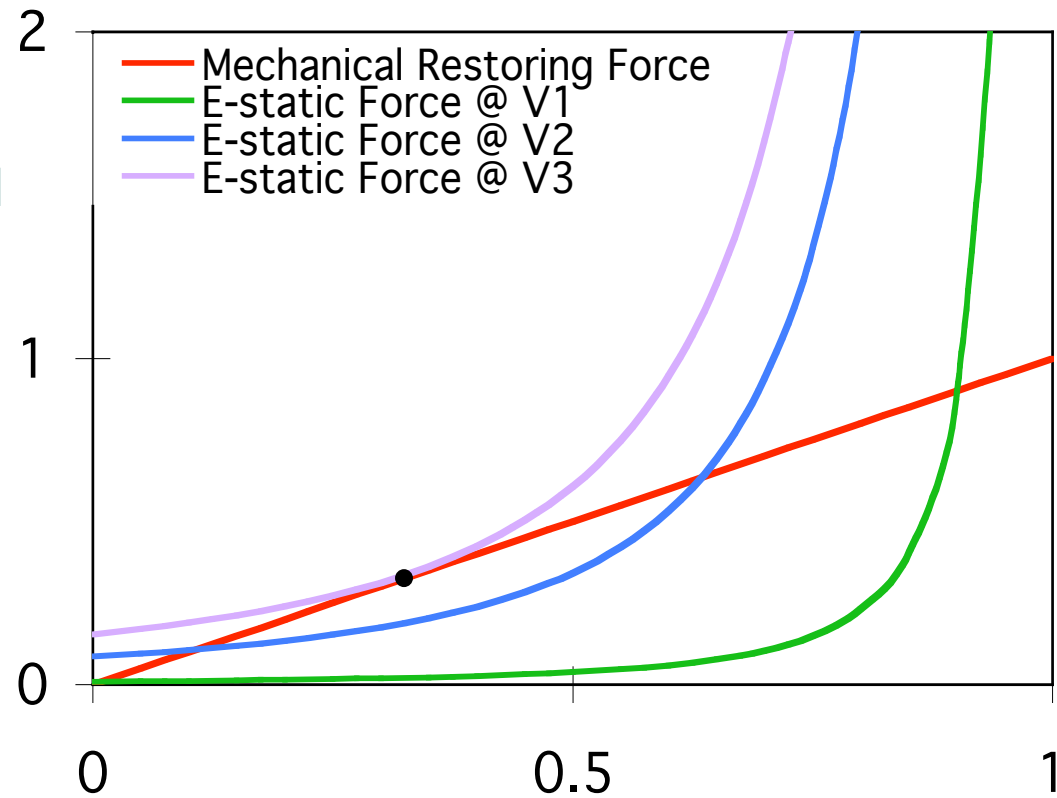


Normalized Displacement (x/g_0)

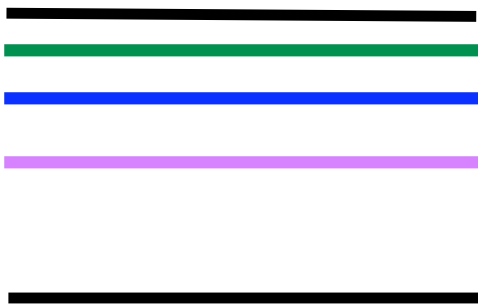
Graphical representation of equilibrium

Critical
Equilibrium

Normalized
Force
 $F/F_{m(max)}$



Normalized Displacement (x/g_0)



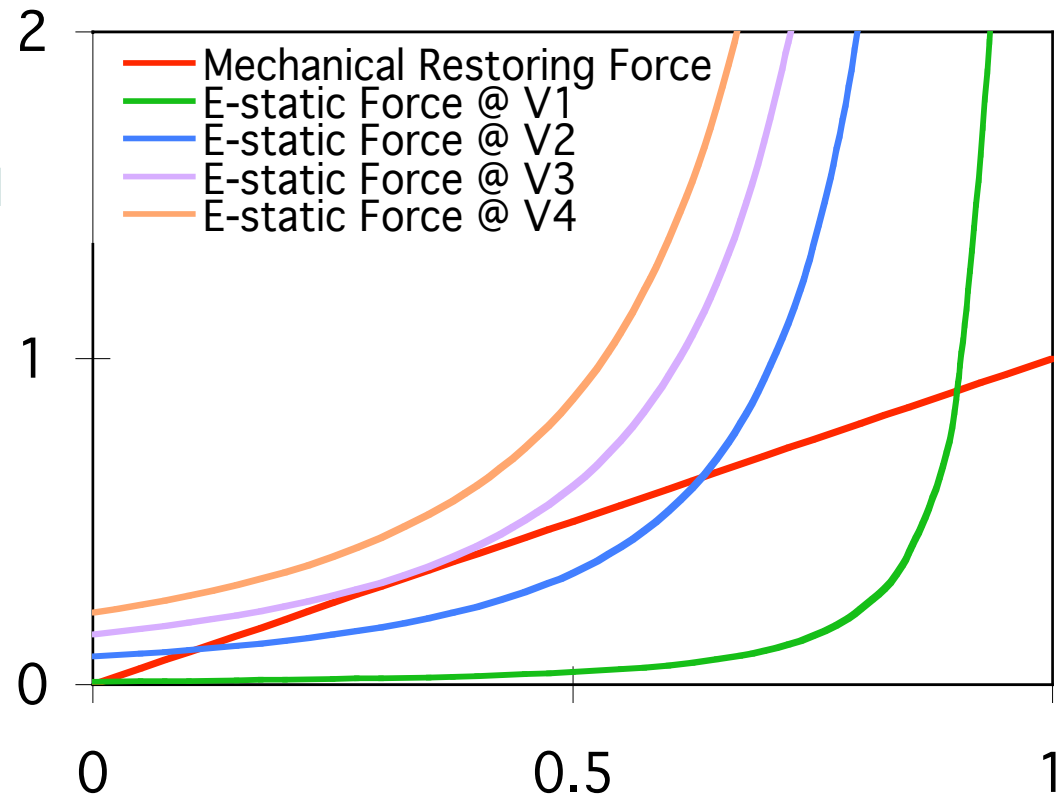
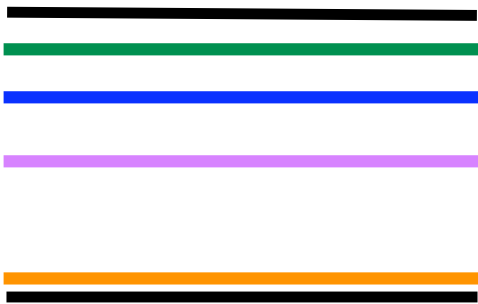
Graphical representation of equilibrium

Unstable

$$F_e > F_m$$

(Newton's
second law:
 $F=ma$)

Normalized
Force
 $F/F_{m(max)}$



Normalized Displacement (x/g_0)

At critical equilibrium

$$F_e = F_m \quad \frac{\varepsilon_o \varepsilon_r L W V^2}{2(g_o - x)^2} = kx$$

$$\left. \frac{dF_e}{dx} \right|_{x_c} = \left. \frac{dF_m}{dx} \right|_{x_c} \quad \text{Curves are tangent}$$

$$\frac{\varepsilon_o \varepsilon_r L W V_c^2}{(g_o - x_c)^3} = k$$

Substitute into equilibrium eqn:

$$\frac{\varepsilon_o \varepsilon_r L W V_c^2}{(g_o - x_c)^3} x_c = \frac{\varepsilon_o \varepsilon_r L W V_c^2}{2(g_o - x_c)^2}$$

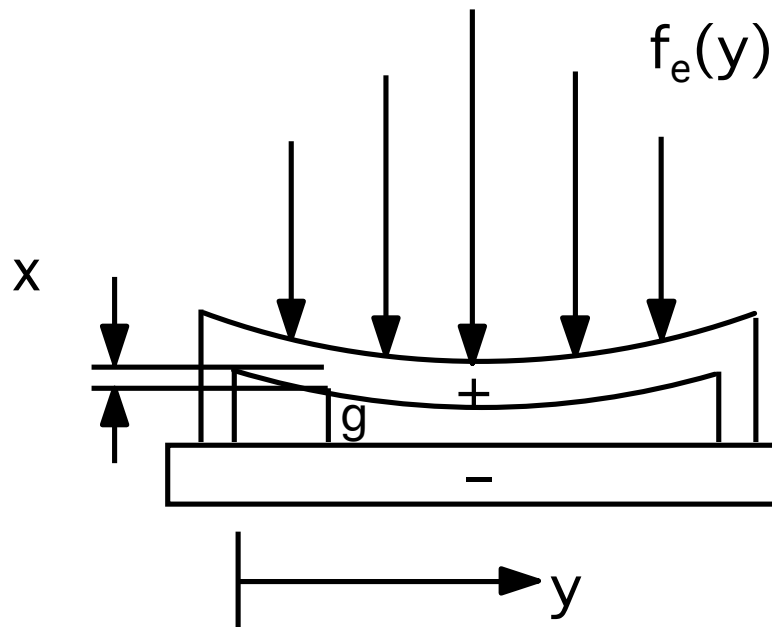
$$x_c = \frac{g_o}{3}$$

Independent of
actuator stiffness

Critical voltage is maximum
required to drive actuator

$$V_c = \sqrt{\frac{8kg_o^3}{27\varepsilon_o\varepsilon_rLW}}$$

Real actuator is not a parallel plate, but a bending fixed-fixed beam



$$k \sim \frac{192EI}{L^3} = \frac{16Etw}{L^3}$$

E = Elastic modulus

I = Moment of inertia

t = Actuator thickness

BMC μ DM140:

$$V_c \sim \sqrt{\frac{5Et^3g_o^3}{\epsilon_o\epsilon_rL^4}}$$

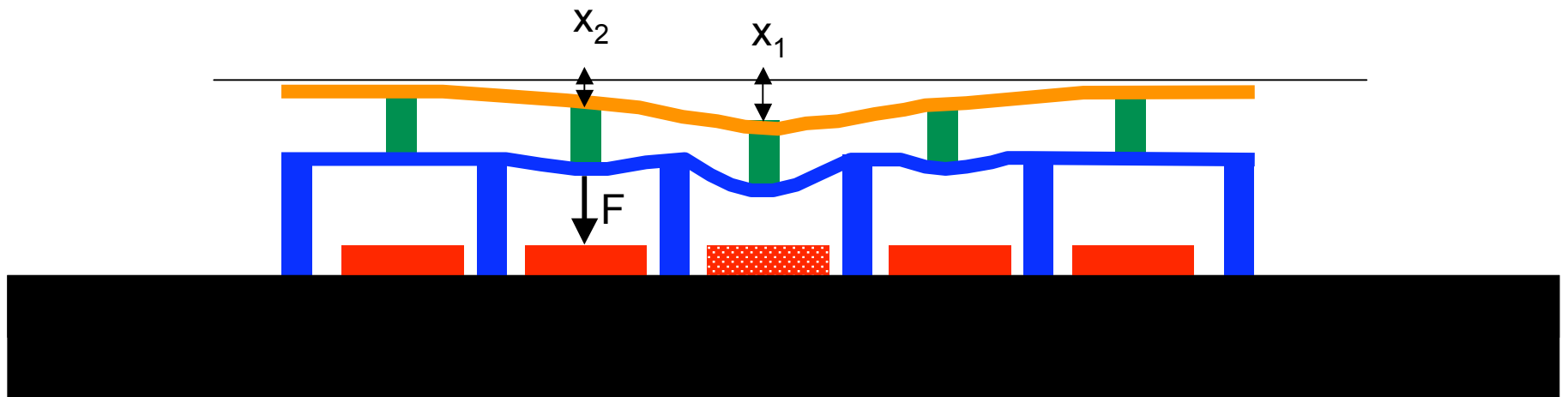
$$V_c = \sqrt{\frac{5 * 170e^9 * (3e^{-6})^3 * (5e^{-6})^3}{8.8e^{-12} * 1 * (3e^{-4})^4}} \sim 200V$$

Real actuator is not a parallel plate, but a bending fixed-fixed beam

Good news: fixed fixed beam improves stroke:

$$x_c \sim 0.4g_o$$

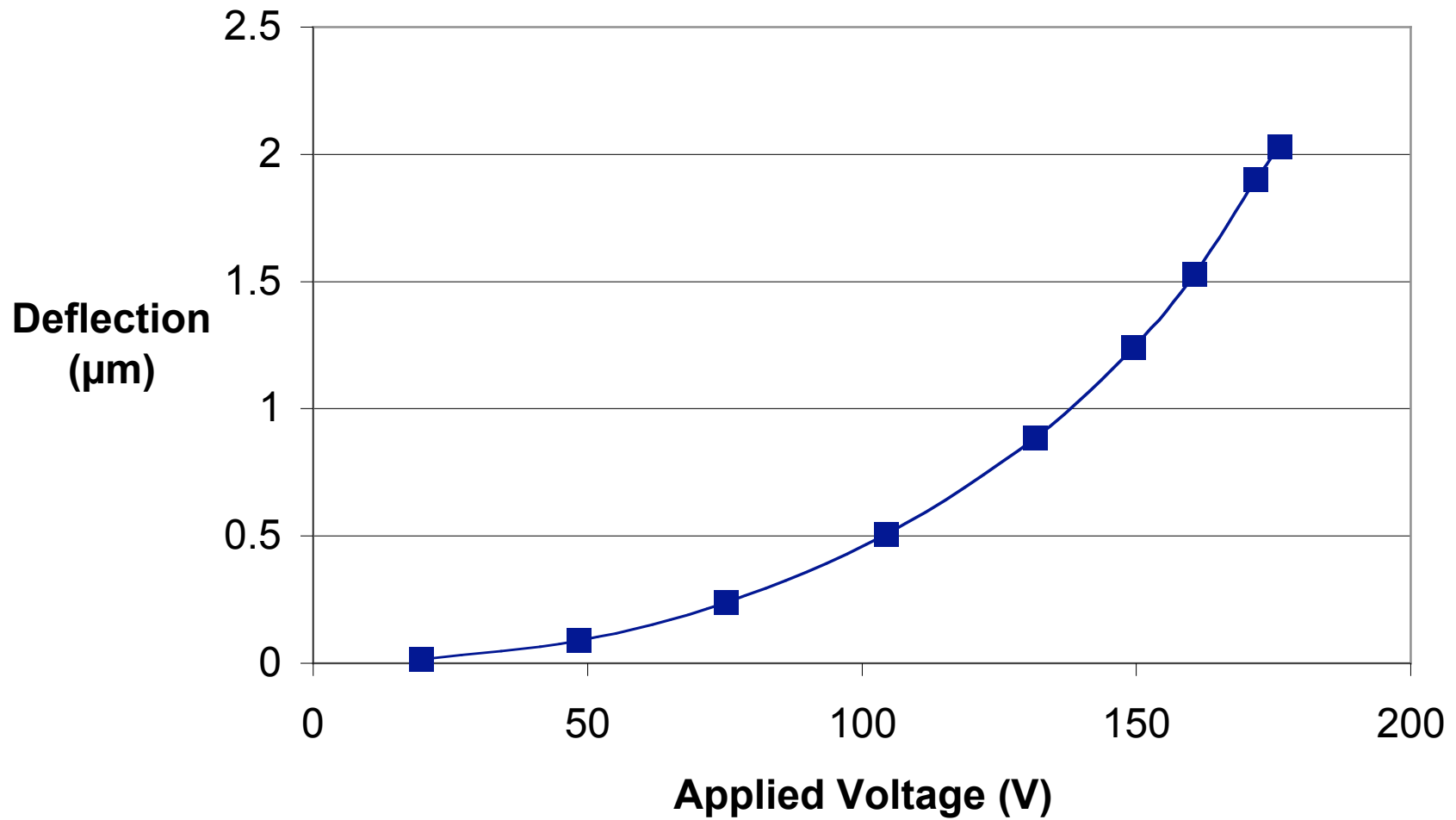
The mirror adds an additional mechanical force



Energized central actuator exerts a force on its unenergized neighbors

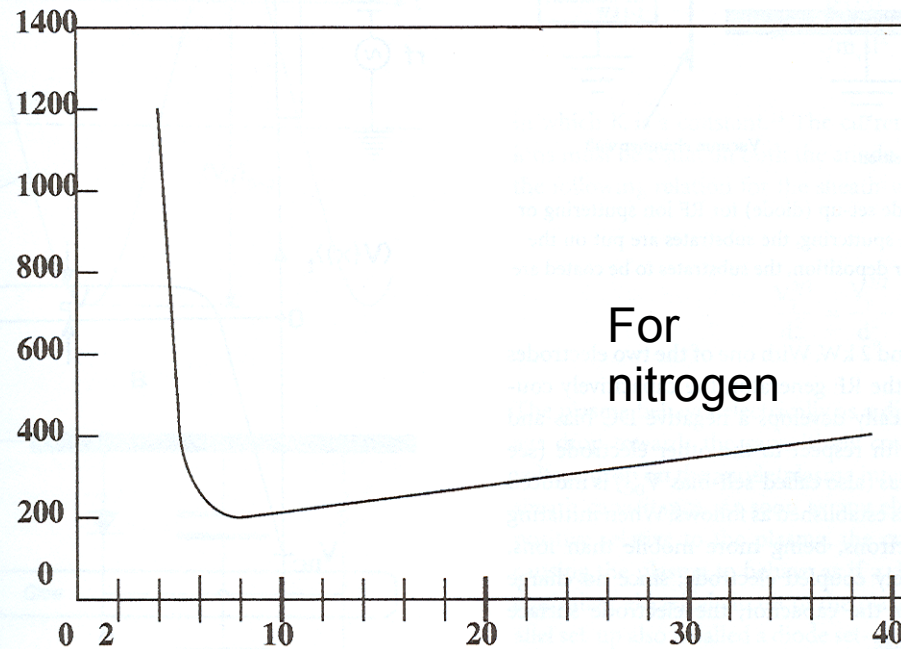
Influence: x_2/x_1 is determined by the relative stiffness of mirror and actuator. For different BMC designs, influence ranges from 0.00 to 0.25

Voltage versus deflection is nonlinear



There is a voltage limitation for parallel plate actuation

Breakdown Voltage (V)



For
nitrogen

Pressure*gap ($\mu\text{m-atm}$)

Minimum breakdown voltage as a function of gas

Gas	Vs min (V)	pd at Vs min (torr cm)
Air	327	0.567
Ar	137	0.9
H2	273	1.15
He	156	4.0
CO2	420	0.51
N2	251	0.67
N2O	418	0.5
O2	450	0.7
SO2	457	0.33
H2S	414	0.6

Gap at minimum
(press. = 1 atm.)

8
12
15
53
7
9
7
9
4
8

Naidu, M.S. and Kamaraju, V., High Voltage Engineering, 2nd ed., McGraw Hill, 1995, ISBN 0-07-462286-2

Additional factors in design and performance

Film stresses (usually $\sim 10\text{MPa}$ compressive)

Cause actuator buckling, leading to smaller initial gap

- Buckling amplitude increases with L
- Process control can help

Cause mirror nonplanarity

- 30nm RMS typical, 10nm RMS achievable
- 1nm will require thicker mirror or different material

Spring nonlinearity (strain stiffening)

As actuator deflects, the membrane lengthens

- 50MPa change in stress with $5\mu\text{m}$ deflection
- This helps linearize voltage versus deflection curve!

Scaling the technology

More stroke: increase gap g_o or critical deflection ratio (x_c/g_o)

4.5 μ m is current maximum

10 μ m is possible with current processes

More actuators: increase array size up to wafer scale (140mm)

~150,000 actuators

requires through-wafer via connections to integrated driver electronics



Resolution

Electrostatic actuation exhibits no hysteresis

Operation requires infinitesimal power (100fF capacitor)

13pm repeatability measured on actuator at JPL (2nm at BU)

*Current driver has 8-bit voltage resolution, and offers resolution of about 1% of FS deflection.

Design modification case study: Double stroke

A CfAO sponsored effort

Recall that :

$$V_c \propto g_o^{3/2}, L^2, k^{1/2}$$

Initial device design

gap	5 μ m
V_c	150V
stroke	2 μ m
x_c/g_o	0.4
L	300 μ m

Design modification case study: Double stroke

Step 1: Increase gap, by thickening actuator sacrificial layer

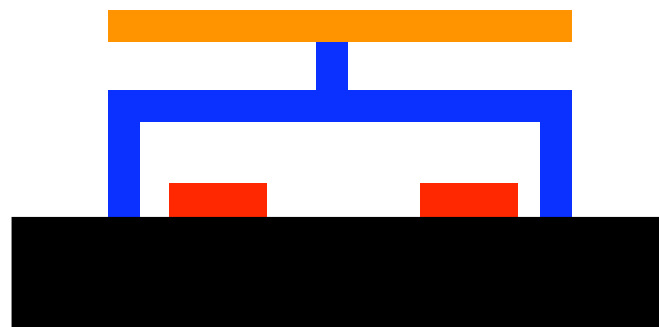
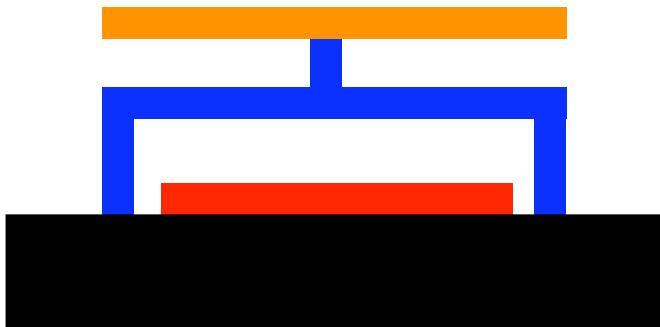
$$\frac{g_o^*}{g_o} = 1.5 \quad \therefore \quad \frac{V_c^*}{V_c} = 3.7 \quad \frac{x_c^*}{x_c} = 1.5$$



Design modification case study: Double stroke

Step 2: Increase stability over a larger gap fraction, by splitting electrodes (can get 60% of gap)

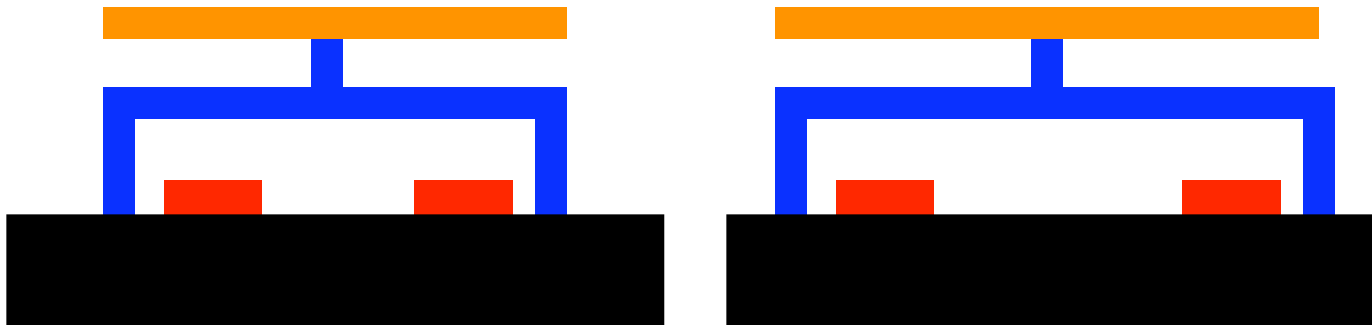
$$\frac{\frac{x_c}{g_o}}{\frac{x_c}{g_o}} = 1.5 \quad \therefore \quad \frac{V_c^*}{V_c} \sim 2 \quad \frac{x_c^*}{x_c} = 1.5$$



Design modification case study: Double stroke

Step 3: Increase actuator length, by altering mask layout

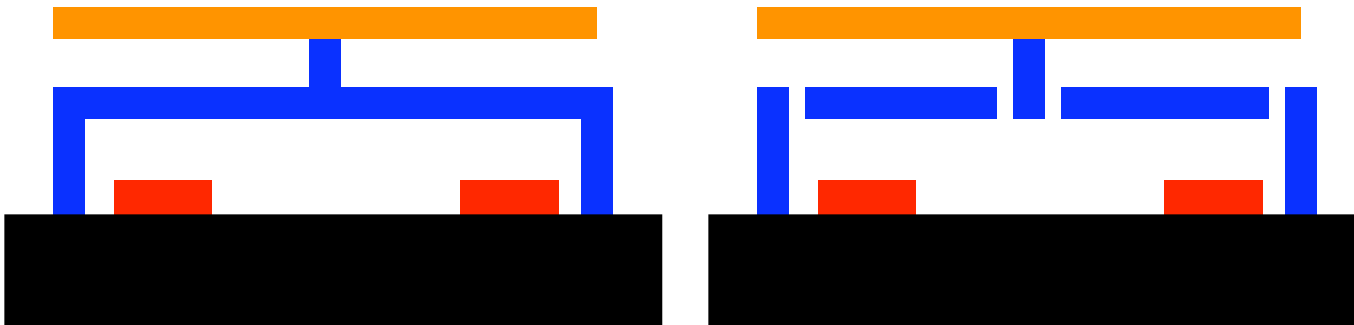
$$\frac{L^*}{L} = 1.3 \quad \therefore \quad \frac{V_c^*}{V_c} \sim 0.6 \quad \frac{x_c^*}{x_c} = 1$$



Design modification case study: Double stroke

Step 4: Decrease actuator stiffness, by perforating membrane

$$\frac{k^*}{k} \sim 0.25 \quad \therefore \quad \frac{V_c^*}{V_c} \sim 0.5 \quad \frac{x_c^*}{x_c} = 1$$



Design modification case study: Double stroke

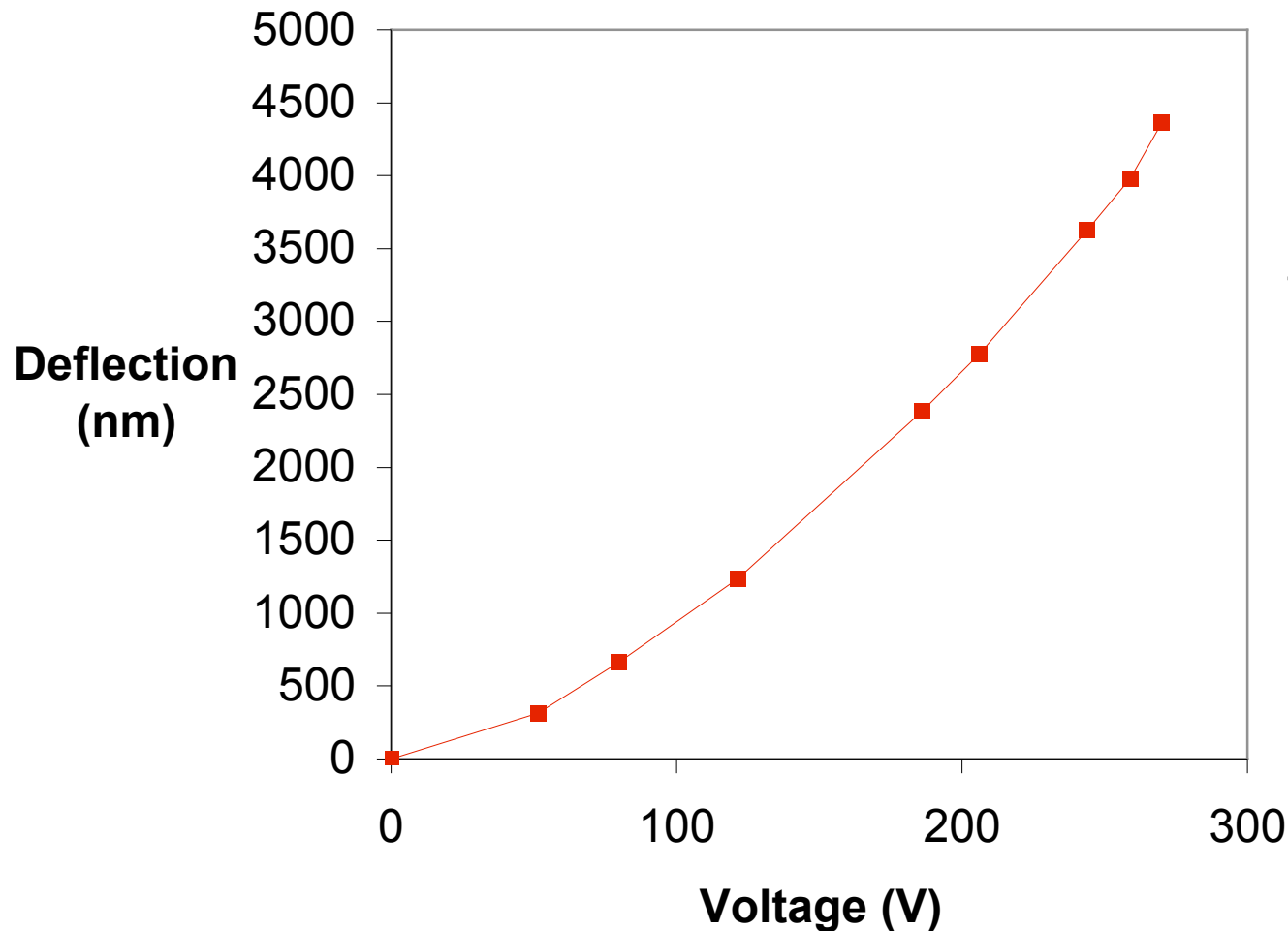
Net result:

$$\frac{V_c^*}{V_c} \sim 3.7 * 2 * 0.6 * 0.5 \sim 2.2$$

$$\frac{X_c^*}{X_c} \sim 1.5 * 1.5 * 1 * 1 \sim 2.2$$



Design modification case study: Double stroke



Unexpected benefit:
Split electrodes
prevent failure due
to overvoltage
instability

Unexpected liability:
RMS figure of mirror
increased due to
actuator compliance

Conclusions

Parallel plate actuation is a robust, reliable approach to MEMS DM development. Its simplicity allows deterministic design. It provides a proven platform for future high-resolution DMs.